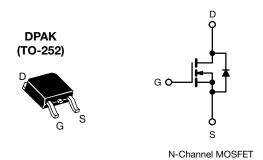
Vishay Siliconix

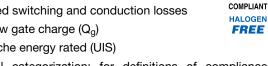
E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.320		
Q _g max. (nC)	52			
Q _{gs} (nC)	6			
Q _{gd} (nC)	13			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION			
Package	DPAK (TO-252)		
Lead (Pb)-free and halogen-free	SiHD9N60E-GE3		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	- I _D	9	А	
		T _C = 100 °C		6		
Pulsed drain current ^a			I _{DM}	22	1	
Linear derating factor				0.63	W/°C	
Single pulse avalanche energy b			E _{AS}	111	mJ	
Maximum power dissipation			P_{D}	78	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C		70		1//20	
Reverse diode dV/dt ^d		dV/dt	40	- V/ns		
Soldering recommendations (peak temperature) ^c	For 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.8 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.

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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R_{thJA}	=	62	°C/W		
Maximum Junction-to-Case (Drain)	R_{thJC}	-	1.6	G/VV		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static					•	•	
Drain-source breakdown voltage	V _{DS}	V _{GS} :	600	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.71	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4.5	V
Cata assuras lagicara	1	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I _{GSS}		V _{GS} = ± 30 V		-	± 1	μΑ
		V _{DS} =	= 600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 4.5 A	-	0.320	0.368	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 4.5 A		-	2.4	-	S
Dynamic		•					
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	778	-	pF
Output capacitance	C _{oss}			-	48	-	
Reverse transfer capacitance	C _{rss}			1	4	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	29	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	138	-	
Total gate charge	Qg		V _{GS} = 10 V I _D = 4.5 A, V _{DS} = 480 V	1	26	52	
Gate-source charge	Q _{gs}	V _{GS} = 10 V		1	6	-	nC
Gate-drain charge	Q _{gd}	1 1		-	13	-	1
Turn-on delay time	t _{d(on)}			-	14	28	- ns
Rise time	t _r	V _{DD} =	$V_{DD} = 480 \text{ V}, I_D = 4.5 \text{ A},$		13	26	
Turn-off delay time	t _{d(off)}	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		-	31	62	
Fall time	t _f			-	12	24	
Gate input resistance	R_g	f = 1 MHz, open drain		0.4	1.2	2.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	9	
Pulsed diode forward current	I _{SM}			-	-	22	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 4.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25$ °C, $I_F = I_S = 4.5$ A, $I_R = 100$ A/ μ s, $I_R = 25$ V		-	207	414	ns
Reverse recovery charge	Q _{rr}			-	2.2	4.4	μC
Reverse recovery current	I _{RRM}			-	20	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

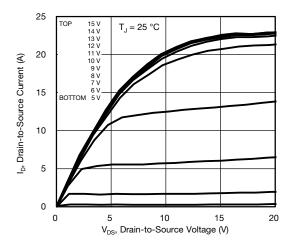


Fig. 1 - Typical Output Characteristics

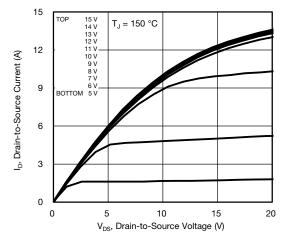


Fig. 2 - Typical Output Characteristics

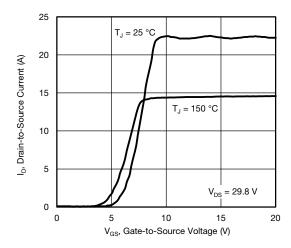


Fig. 3 - Typical Transfer Characteristics

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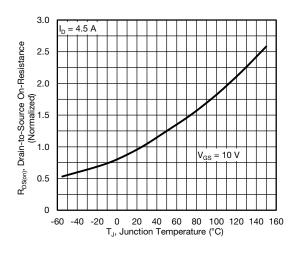


Fig. 4 - Normalized On-Resistance vs. Temperature

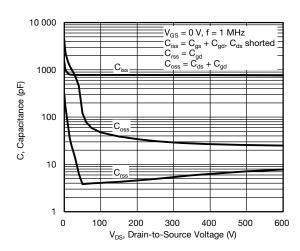


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

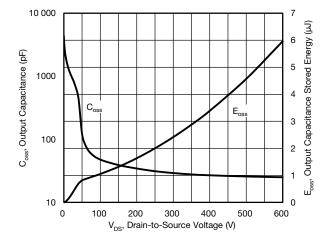


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



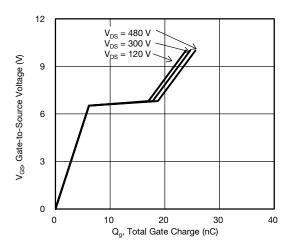


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

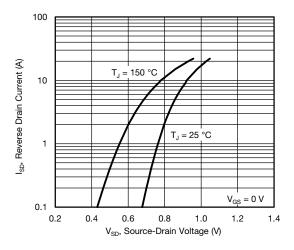


Fig. 8 - Typical Source-Drain Diode Forward Voltage

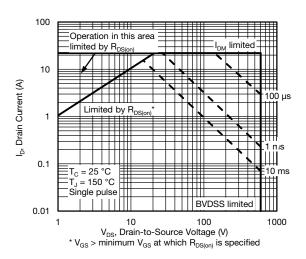


Fig. 9 - Maximum Safe Operating Area

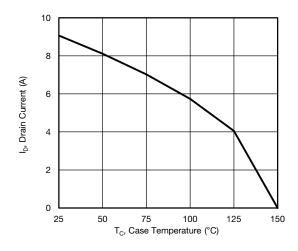


Fig. 10 - Maximum Drain Current vs. Case Temperature

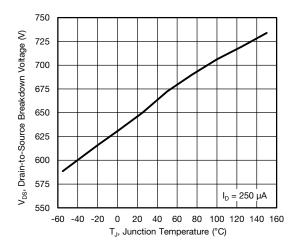


Fig. 11 - Temperature vs. Drain-to-Source Voltage



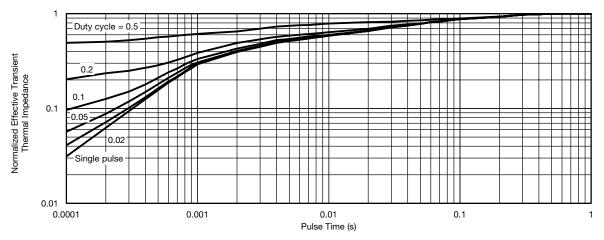


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

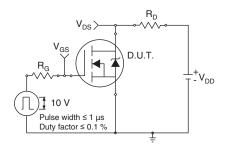


Fig. 13 - Switching Time Test Circuit

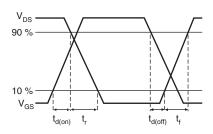


Fig. 14 - Switching Time Waveforms

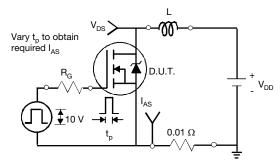


Fig. 15 - Unclamped Inductive Test Circuit

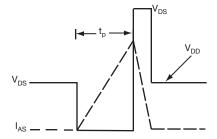


Fig. 16 - Unclamped Inductive Waveforms

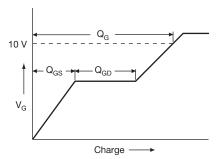


Fig. 17 - Basic Gate Charge Waveform

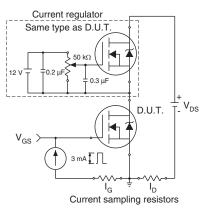
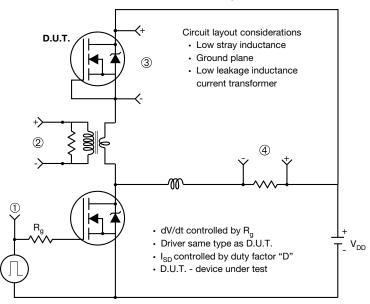


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



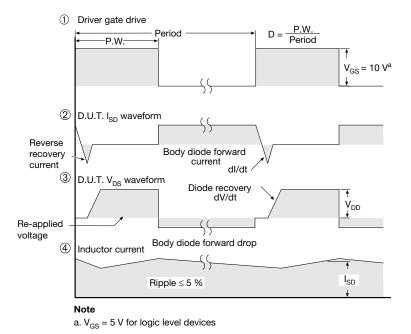


Fig. 19 - For N-Channel

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